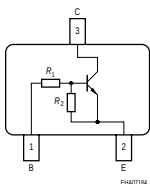


NPN Silicon Digital Transistor

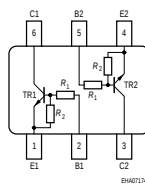
- Switching circuit, inverter, interface circuit driver circuit
- Built in bias resistor ($R_1=10\text{ k}\Omega$, $R_2=47\text{ k}\Omega$)
- BCR135S: Two internally isolated transistors with good matching in one multichip package
- BCR135S: For orientation in reel see package information below
- Pb-free (RoHS compliant) package
- Qualified according AEC Q101



BCR135 BCR135W



BCR135S



Type	Marking	Pin Configuration						Package
BCR135	WJs	1=B	2=E	3=C	-	-	-	SOT23
BCR135S	WJs	1=E1	2=B1	3=C2	4=E2	5=B2	6=C1	SOT363
BCR135W	WJs	1=B	2=E	3=C	-	-	-	SOT323

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CEO}	50	V
Collector-base voltage	V_{CBO}	50	
Input forward voltage	$V_{i(fwd)}$	40	
Input reverse voltage	$V_{i(rev)}$	6	
Collector current	I_C	100	mA
Total power dissipation	P_{tot}		mW
BCR135, $T_S \leq 102^\circ\text{C}$		200	
BCR135S, $T_S \leq 115^\circ\text{C}$		250	
BCR135W, $T_S \leq 124^\circ\text{C}$		250	
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-65 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R_{thJS}		K/W
BCR135		≤ 240	
BCR135S		≤ 140	
BCR135W		≤ 105	

¹⁾For calculation of R_{thJA} please refer to Application Note AN077 (Thermal Resistance Calculation)

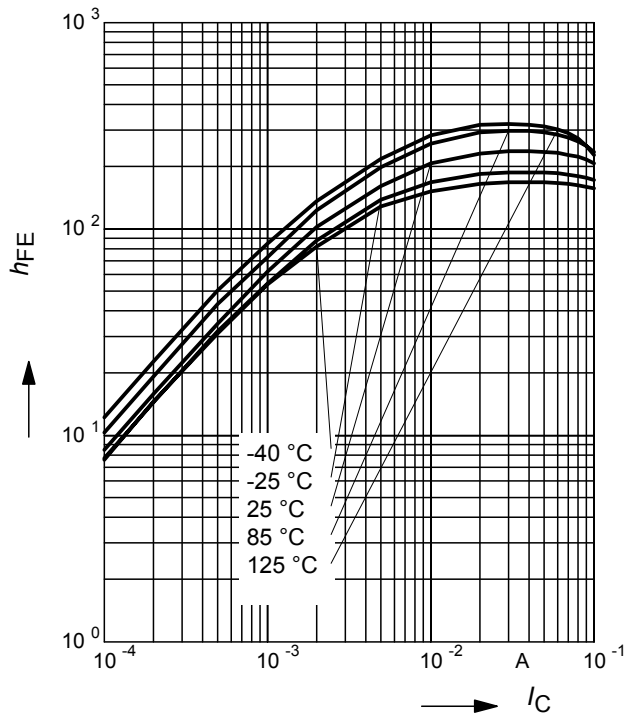
Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage $I_C = 100\ \mu\text{A}$, $I_B = 0$	$V_{(\text{BR})\text{CEO}}$	50	-	-	V
Collector-base breakdown voltage $I_C = 10\ \mu\text{A}$, $I_E = 0$	$V_{(\text{BR})\text{CBO}}$	50	-	-	
Collector-base cutoff current $V_{\text{CB}} = 40\ \text{V}$, $I_E = 0$	I_{CBO}	-	-	100	nA
Emitter-base cutoff current $V_{\text{EB}} = 6\ \text{V}$, $I_C = 0$	I_{EBO}	-	-	167	μA
DC current gain ¹⁾ $I_C = 5\ \text{mA}$, $V_{\text{CE}} = 5\ \text{V}$	h_{FE}	70	-	-	-
Collector-emitter saturation voltage ¹⁾ $I_C = 10\ \text{mA}$, $I_B = 0.5\ \text{mA}$	V_{CEsat}	-	-	0.3	V
Input off voltage $I_C = 100\ \mu\text{A}$, $V_{\text{CE}} = 5\ \text{V}$	$V_{\text{i(off)}}$	0.5	-	1	
Input on voltage $I_C = 2\ \text{mA}$, $V_{\text{CE}} = 0.3\ \text{V}$	$V_{\text{i(on)}}$	0.5	-	1.4	
Input resistor	R_1	7	10	13	k Ω
Resistor ratio	R_1/R_2	0.19	0.21	0.24	-
AC Characteristics					
Transition frequency $I_C = 10\ \text{mA}$, $V_{\text{CE}} = 5\ \text{V}$, $f = 100\ \text{MHz}$	f_{T}	-	150	-	MHz
Collector-base capacitance $V_{\text{CB}} = 10\ \text{V}$, $f = 1\ \text{MHz}$	C_{cb}	-	3	-	pF

¹⁾Pulse test: $t < 300\ \mu\text{s}$; $D < 2\%$

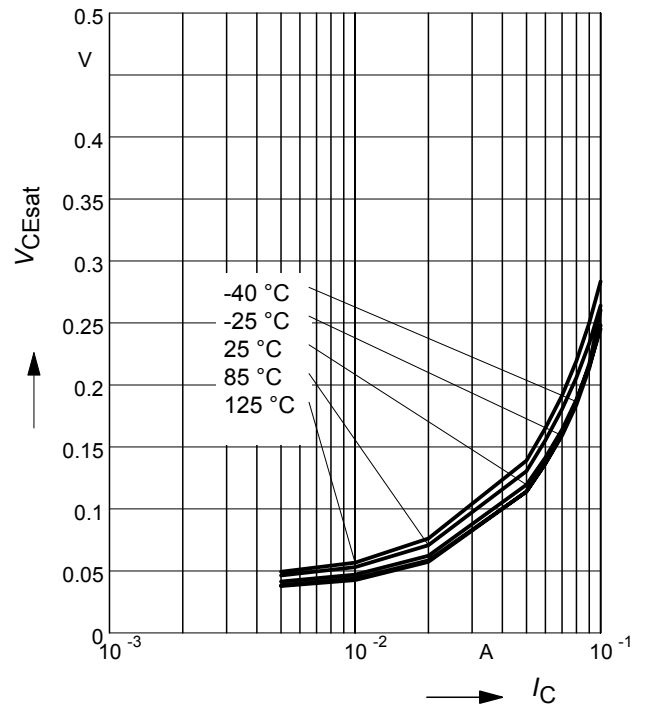
DC current gain $h_{FE} = f(I_C)$

$V_{CE} = 5V$ (common emitter configuration)



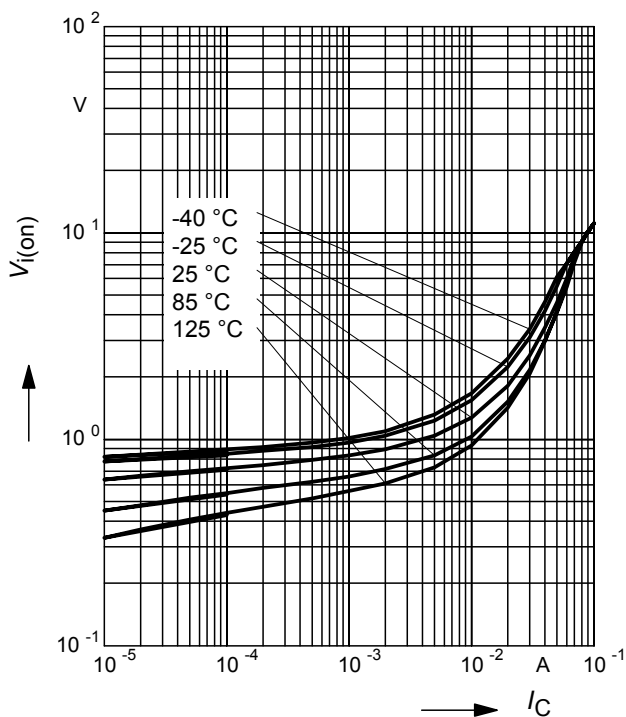
Collector-emitter saturation voltage

$V_{CEsat} = f(I_C)$, $I_C/I_B = 20$



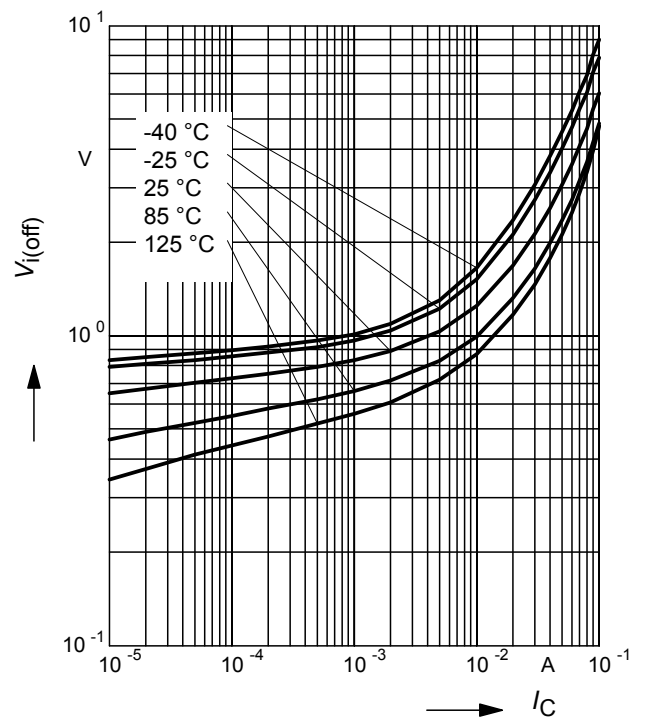
Input on Voltage $V_{i(on)} = f(I_C)$

$V_{CE} = 0.3V$ (common emitter configuration)



Input off voltage $V_{i(off)} = f(I_C)$

$V_{CE} = 5V$ (common emitter configuration)



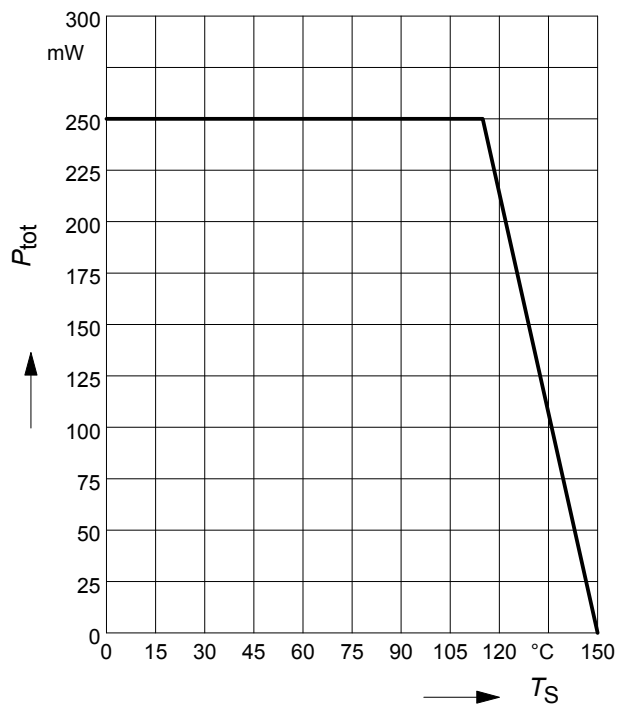
Total power dissipation $P_{\text{tot}} = f(T_S)$

BCR135



Total power dissipation $P_{\text{tot}} = f(T_S)$

BCR135S



Total power dissipation $P_{\text{tot}} = f(T_S)$

BCR135W



Permissible Pulse Load $R_{\text{thJS}} = f(t_p)$

BCR135



Permissible Pulse Load

$$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$$

BCR135



Permissible Puls Load $R_{\text{thJS}} = f(t_p)$

BCR135S



Permissible Pulse Load

$$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$$

BCR135S



Permissible Puls Load $R_{\text{thJS}} = f(t_p)$

BCR135W



Permissible Pulse Load

$$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$$

BCR135W





Technical drawing of a mechanical part with dimensions: 0.8, 0.9, 1.3, 0.8, 1.2, 0.9.

The diagram shows a top-down view of a BCW66 LED package. It is a rectangular component with four pins. The top pin is labeled 'Pin 1'. The package has a central rectangular area containing the text 'EH S' and a date code '2005, June' (represented as '05' over '06'). The Infineon logo is visible in the top right corner. Labels with leader lines point to the Infineon logo (Manufacturer), the date code (Date code (YM)), and the 'BCW66' type code (Type code).

Package Outline



Foot Print



Marking Layout (Example)



Standard Packing

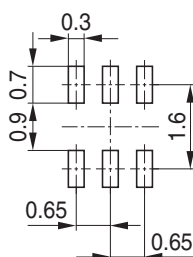
Reel $\varnothing 180$ mm = 3.000 Pieces/Reel
 Reel $\varnothing 330$ mm = 10.000 Pieces/Reel



Package Outline

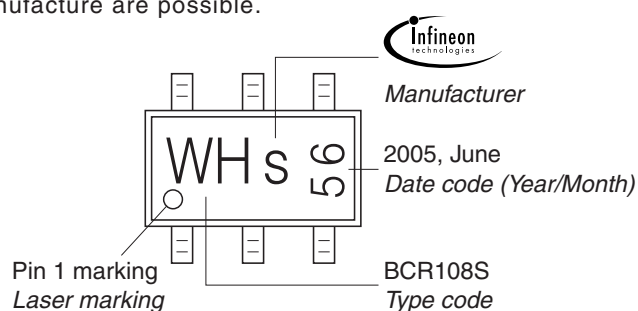


Foot Print



Marking Layout (Example)

Small variations in positioning of
Date code, Type code and Manufacture are possible.



Standard Packing

Reel $\varnothing 180 \text{ mm}$ = 3.000 Pieces/Reel
Reel $\varnothing 330 \text{ mm}$ = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.



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